

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon (Si)	7440-21-3	0	0.0	0
		Subtotal		0	0	0
Wire	Pure metal	Aluminium (Al)	7429-90-5	0	100.0	0.32
	Pure metal	Aluminium (Al)	7429-90-5	0.16	100.0	11.52
		Subtotal		0.16	200	11.84
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.16	65.0	11.86
	Lead alloy	Silver (Ag)	7440-22-4	0.06	25.0	4.56
	Lead alloy	Antimony (Sb)	7440-36-0	0.02	10.0	1.83
		Subtotal		0.24	100	18.25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	1.46
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	4.86
	Copper alloy	Copper (Cu)	7440-50-8	66.01	99.87	4849.69
		Subtotal		66.1	100	4856.01
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.32	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.96	15.0	364.5
	Filler	Silica fused	60676-86-0	24.47	74.0	1798.2
	Flame retardant	Metal hydroxide		2.32	7.0	170.1
		Subtotal		33.07	100	2430
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.41	100.0	30
		Subtotal		0.41	100	30
		Total		99.98	100	7346.1

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